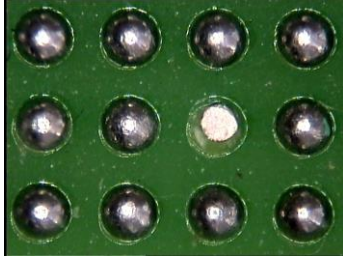


ScanINSPECT BPI™

Ball Placement Inspection



0.3 mm balls

WHAT IS ScanINSPECT BPI?

ScanINSPECT BPI provides a fast, simple and user-friendly alternative to inaccurate and time-consuming manual inspection methods or expensive, yet slow, measurement systems.

ScanINSPECT BPI uses an intuitive process flow interface integrated with a high resolution, Color, 2-D image-processing unit. This combination allows 100% inspection of ball or bump placement on a wide variety of substrates and device types including FR4, Ceramic, Wafer, Flip chip, BGA, CSP, etc. The system can be used either pre or post reflow.

HOW DOES ScanINSPECT WORK?

ScanINSPECT's integration within the production environment provides inspection of ball or bump:

- Presence/Absence
- Size
- Position

Each device or substrate is placed into ScanINSPECT for 100% inspection. The balls or bumps are inspected and any errors are displayed on the screen. The system is barcode reader compatible.

FAST & SIMPLE PROGRAMMING

ScanINSPECT BPI is quickly programmed from a golden part in a few minutes. Corrections to the golden part can be quickly and easily made, if necessary.

INCREASE YIELD & IMPROVE OVERALL PRODUCTIVITY

ScanINSPECT BPI's powerful 100% inspection process increases product yield by ensuring accurate ball or bump placement. Missing balls or bumps can result in reduced yield, lost production time and extensive rework.

Missing or misplaced balls or bumps are now automatically detected. Problems are identified and eliminated before substrates or devices are reflowed, permitting quick and easy rework.

Problems are identified and eliminated **before** substrates or devices are reflowed, permitting quick and easy rework. The same system is also able to perform a final inspection after reflow. In production, each device or tray is placed on the table, shuttled in, automatically aligned and checked for accuracy with a PASS or FAIL inspection in seconds.

WHY USE ScanINSPECT?

- **Mandatory:** 100% automatic inspection of ball or bump placement, pre and/or post reflow.
- **Security:** Confirm ball/bump absence / presence.
- **Traceability:** Full inspection documentation of every ball down to the device serial number & lot number level.
- **Necessity:** Detect errors *before* reflow permitting easy rework.



DESKTOP MODULE

System Specifications*

- Maximum Substrate Size: 18" X 24" (457mm X 610mm)
- Maximum Inspection Area: 11.7" X 16.5" (297mm X 419mm)
- Ball/Bump Diameter Range: 0.050 mm to 6 mm
- Resolution: Range from 200 dpi to 2400 dpi

Footprint of Inspection Unit

- Depth: 31.5" (800mm), table extended 49.5" (1,257mm)
- Width: 27.25" (692mm)
- Height: 19" (482mm)
- Weight: 150lbs. (55.95kg)

Computer*

- Multi Core Processor - 3 GHz
- 1 TB 7200 RPM HD, 8 - 16 GB RAM
- Flat Panel Monitor
- Ethernet Connection
- Windows 10 64-Bit
- 2 avail. USB2 / USB3 +1 Firewire

*Recommended customer supplied minimum PC requirements.

(All specifications and designs subject to change without notice.)

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